

In the claims:

Claims 1-8 (cancelled).

---

B<sup>1</sup> Claim 9 (original): A method of manufacturing a light emitting device, said method comprising the steps of:

forming a light emitting element at a front surface of a substrate;  
bonding a color filter at a back surface of the substrate.

Claim 10 (original): A method of manufacturing a light emitting device, said method comprising the steps of:

forming a semiconductor element and a light emitting element being electrically connected to the semiconductor element at a front surface of a substrate;  
bonding a color filter at a back surface of the substrate.

Claim 11 (original): A method of manufacturing a light emitting device, said method comprising the steps of:

forming a light emitting element at a front surface of a substrate;  
bonding a transparent substrate comprising at least a colored layer at a back surface of the substrate.

Claim 12 (original): A method of manufacturing a light emitting device, said method comprising the steps of:

forming a semiconductor element and a light emitting element being electrically connected to the semiconductor element at a front surface of a substrate;  
bonding a transparent substrate comprising at least a colored layer at a back surface of the substrate.

Claim 13 (original): A method according to claim 11, further comprising the step of:  
bonding an antireflection film or a polarization plate to the transparent substrate.

Claim 14 (original): A method according to claim 11, wherein the transparent substrate comprises a polymeric material.

Claim 15 (original): A method according to claim 9, further comprising the step of:  
polishing the back surface of the substrate by a chemical mechanical polishing method.

Claim 16 (original): A method according to claim 10, further comprising the step of:  
polishing the back surface of the substrate by a chemical mechanical polishing method.

Claim 17 (original): A method according to claim 11, further comprising the step of:  
polishing the back surface of the substrate by a chemical mechanical polishing method.

Claim 18 (original): A method according to claim 12, further comprising the step of:  
bonding an antireflection film or a polarization plate to the transparent substrate.

Claim 19 (original): A method according to claim 12, wherein the transparent substrate comprises a polymeric material.

Claim 20 (original): A method according to claim 12, further comprising the step of:  
polishing the back surface of the substrate by a chemical mechanical polishing method.

---

Claims 21 and 22 (cancelled).

---

Claim 23 (new): A method of manufacturing a light emitting device comprising:  
providing a first substrate having a first surface and a second surface opposite to said the  
first surface;  
forming a first electrode over the first surface of the first substrate;  
forming an electroluminescence layer over the first electrode; and

forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

forming a plurality of color layers over a first surface of a second substrate;

fixing the second substrate to said first substrate with said plurality of color layers interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

unt  
2  
B  
Claim 24 (new): The method according to claim 23 wherein said light emitting device is a passive matrix display device.

Claim 25 (new): The method according to claim 23 wherein said light emitting device is an active matrix display device.

Claim 26 (new): The method according to claim 23 wherein said electroluminescence layer comprises an organic electroluminescence material.

Claim 27 (new): A method of manufacturing a light emitting device comprising:  
providing a first substrate having a first surface and a second surface opposite to said the first surface;

forming a first electrode over the first surface of the first substrate;

forming an electroluminescence layer over the first electrode; and

forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

polishing the second surface of the first substrate to thin the first substrate;

forming a plurality of color layers over a first surface of a second substrate;

fixing the second substrate to the thinned first substrate with said plurality of color layers interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

Claim 28 (new): The method according to claim 27 wherein said light emitting device is a passive matrix display device.

Claim 29 (new): The method according to claim 27 wherein said light emitting device is an active matrix display device.

Claim 30 (new): The method according to claim 27 wherein said electroluminescence layer comprises an organic electroluminescence material.

Claim 31 (new): The method according to claim 27 wherein a thickness of said first substrate after the step of polishing is 300  $\mu\text{m}$  or less.

Claim 32 (new): A method of manufacturing a light emitting device comprising:  
providing a first substrate having a first surface and a second surface opposite to said the first surface;

forming a first electrode over the first surface of the first substrate;

forming an electroluminescence layer over the first electrode; and

forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

providing a second substrate having a first surface and a second surface opposite to said second surface wherein said second substrate comprises a plastic material and each of the first and second surfaces of the second substrate are coated with a protective film;

forming a plurality of color layers over the second substrate;

fixing the second substrate to said first substrate with said plurality of color layers interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

Cont  
B2

Claim 33 (new): The method according to claim 32 wherein said light emitting device is a passive matrix display device.

Claim 34 (new): The method according to claim 32 wherein said light emitting device is an active matrix display device.

Cont  
B2  
Claim 35 (new): The method according to claim 32 wherein said electroluminescence layer comprises an organic electroluminescence material.

Claim 36 (new): The method according to claim 32 wherein said protective film comprises diamond like carbon.

Claim 37 (new): A method of manufacturing a light emitting device comprising:  
providing a first substrate having a first surface and a second surface opposite to said the first surface;

forming a first electrode over the first surface of the first substrate;  
forming an electroluminescence layer over the first electrode;  
polishing the second surface of the first substrate to thin the first substrate;  
forming a second electrode over the electroluminescence layer so that said electroluminescence layer is interposed between said first and second electrodes over the first surface of the first substrate;

providing a second substrate having a first surface and a second surface opposite to said second surface wherein said second substrate comprises a plastic material and each of the first and second surfaces of the second substrate are coated with a protective film;

forming a plurality of color layers over the second substrate;  
fixing the second substrate to the thinned first substrate with said plurality of color layers; interposed therebetween, wherein said second substrate is located at a side of said second surface of the first substrate.

Claim 38 (new): The method according to claim 37 wherein said light emitting device is a passive matrix display device.

Claim 39 (new): The method according to claim 37 wherein said light emitting device is an active matrix display device.

Claim 40 (new): The method according to claim 37 wherein said electroluminescence layer comprises an organic electroluminescence material.

Claim 41 (new): The method according to claim 37 wherein a thickness of said first substrate after the step of polishing is 300  $\mu\text{m}$  or less.

Claim 42 (new): The method of claim 9 wherein the light emitting element comprises an electroluminescence material.

Claim 43 (new): The method of claim 10 wherein the light emitting element comprises an electroluminescence material.

Claim 44 (new): The method of claim 11 wherein the light emitting element comprises an electroluminescence material.

Claim 45 (new): The method of claim 12 wherein the light emitting element comprises an electroluminescence material.

---

cont  
B